

ABSTRACT OF THE DISCLOSURE

Disclosed is a film-forming method, comprising
dispensing from a dispenser nozzle a coating solution,
which is prepared by adding a solid component to a
5 solvent and controlled to be spread on the substrate in
a predetermined range, onto a target substrate to be
processed while relatively moving the dispenser nozzle
and the target substrate so as to form a liquid film on
the entire surface of the target substrate, and
10 arranging a sucking nozzle above and apart from the
target substrate such that the sucking nozzle is not in
contact with the surface of the liquid film so as to
permit the sucking nozzle to suck the solvent vapor
right under the sucking nozzle while moving the sucking
15 nozzle relative to the target substrate, thereby
removing the solvent from the liquid film and, thus,
forming a coated film.